

# *Power-Aware Voltage Tuning for STT-MRAM Reliability*





**Elena I. Vatajelu, R. Rodriguez-Montañés, S. Di Carlo,  
M. Indaco, M. Renovell, P. Prinetto, J. Figueras**



**POLITECNICO  
DI TORINO**



# Memories Today

	SRAM	DRAM	Flash
Cell Size	$120F^2$	$4-6F^2$ 	$4-5 F^2$
Read Access Time	$<1ns$	$20ns$	$25,000ns$
Write1 Access Time	$<1ns$ 	$20ns$	$200,000ns$
Write0 Access Time	$<1ns$	$20ns$	$200,000ns$
Endurance	$>10^{15}$ 	$10^{15}$	$10^4$
Non-volatility	NO	NO	

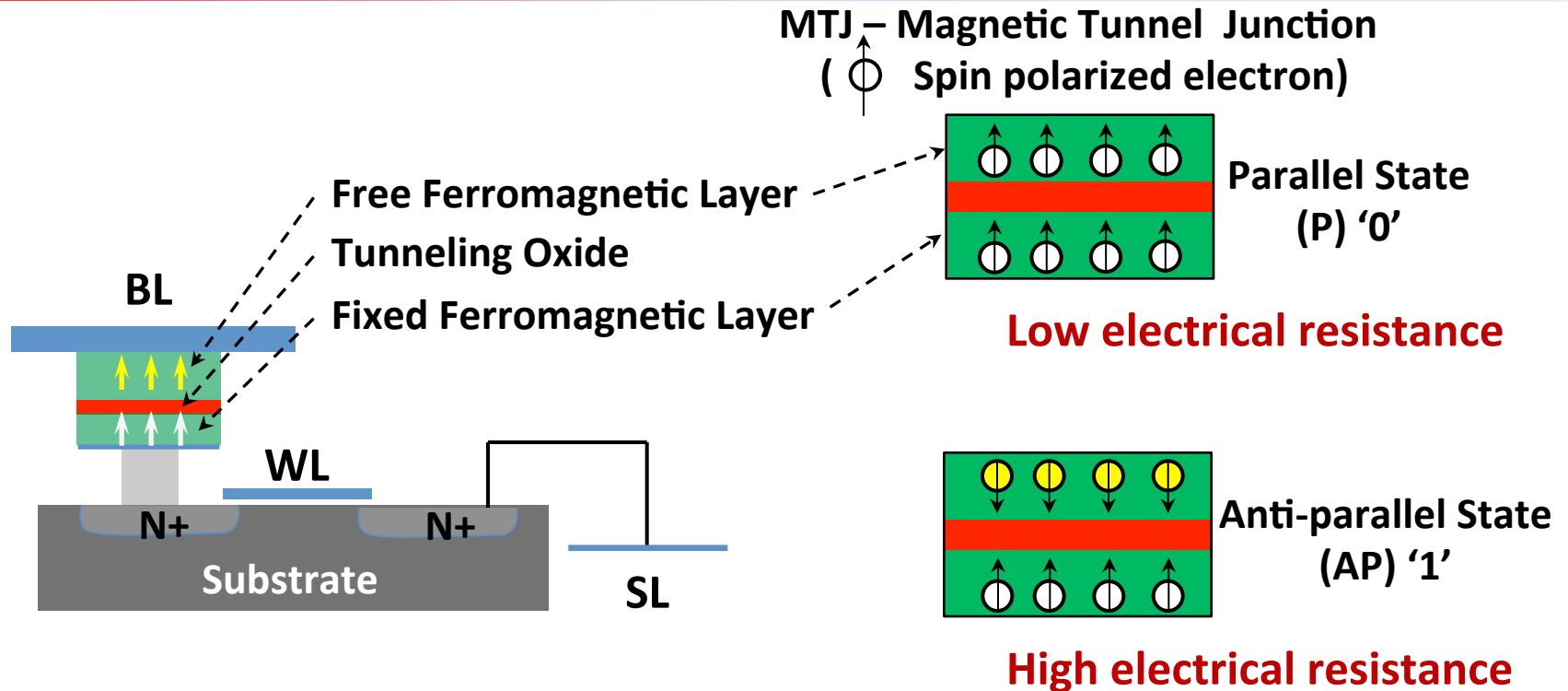
# Outline

- Introduction to STT-MRAM cell
- STT-MRAM cell operation principle
- STT-MRAM parametric reliability analysis
  - Failure mechanisms
  - Control voltage influence on memory cell operation
- STT-MRAM cell reliability estimation
- Conclusions

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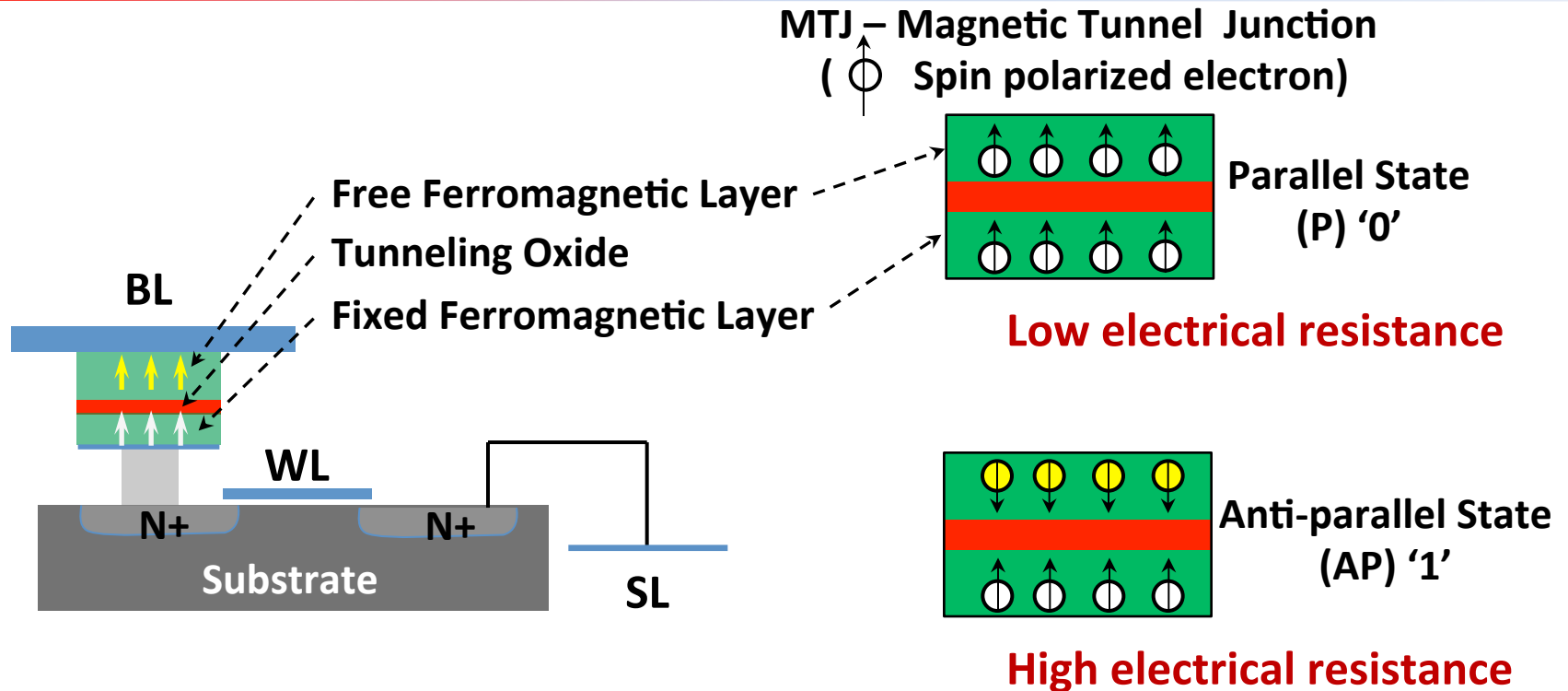
# 1T1MTJ STT-MRAM Cell



The orientation of the free layer:

- determines the **resistance** of the material
- can be changed by injecting **current**.

# 1T1MTJ STT-MRAM Cell



Main resiliency issues come from variations in:

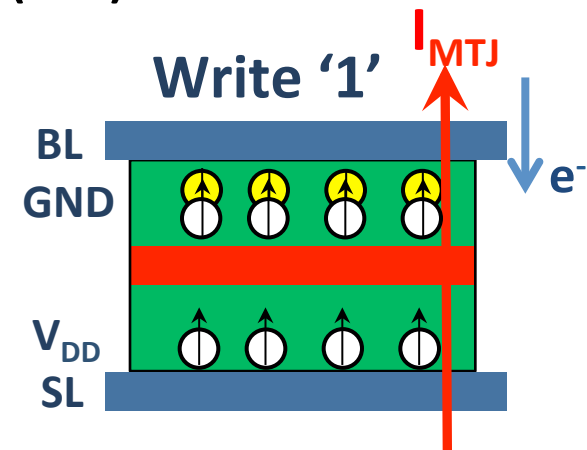
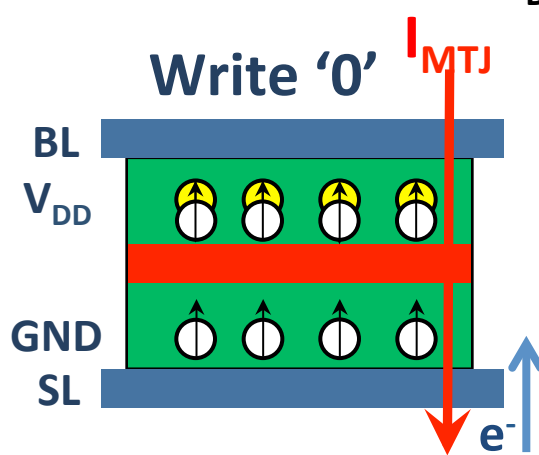
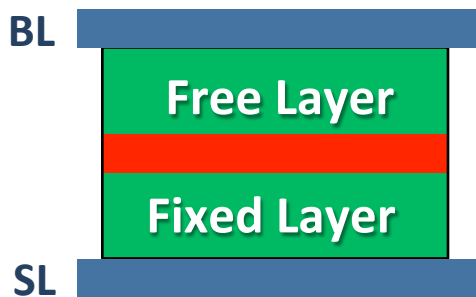
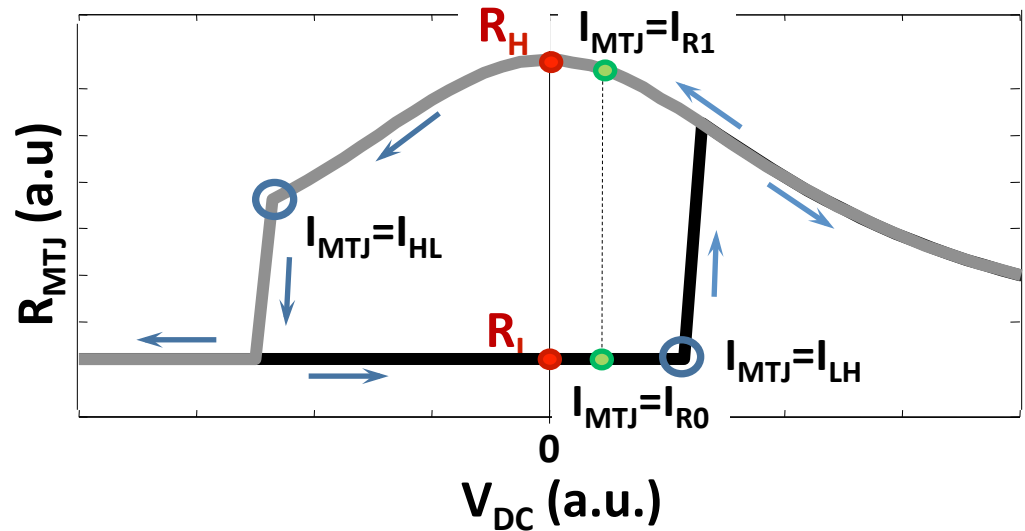
- Tunneling oxide thickness and cross-section area
- Free layer thickness

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# 1T1MTJ STT-MRAM Cell

$I_{HL}$  - high to low transition  
 $I_{LH}$  - low to high transition

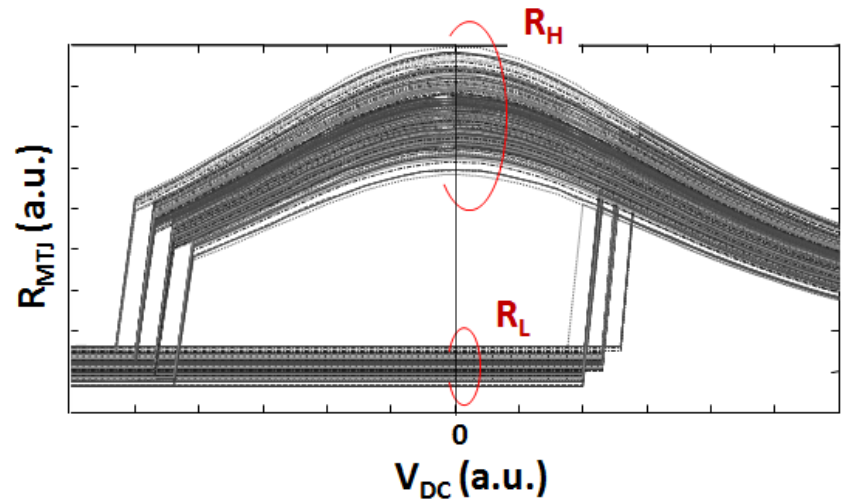
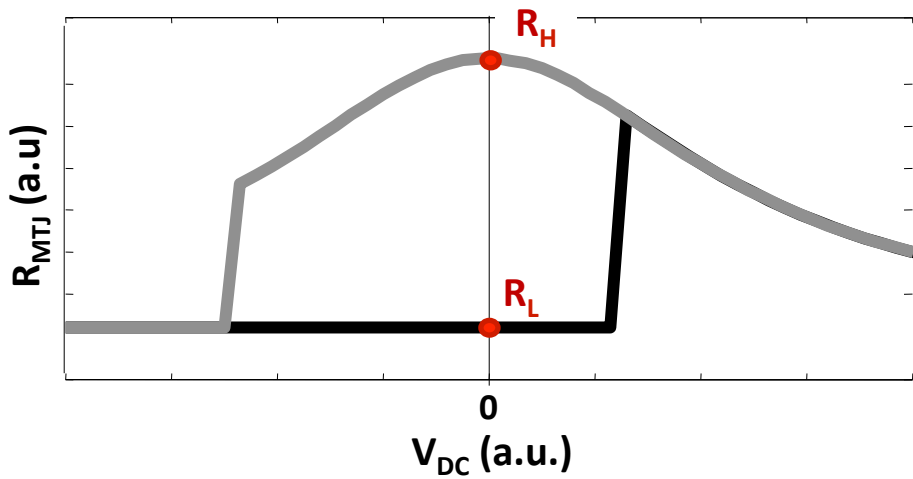




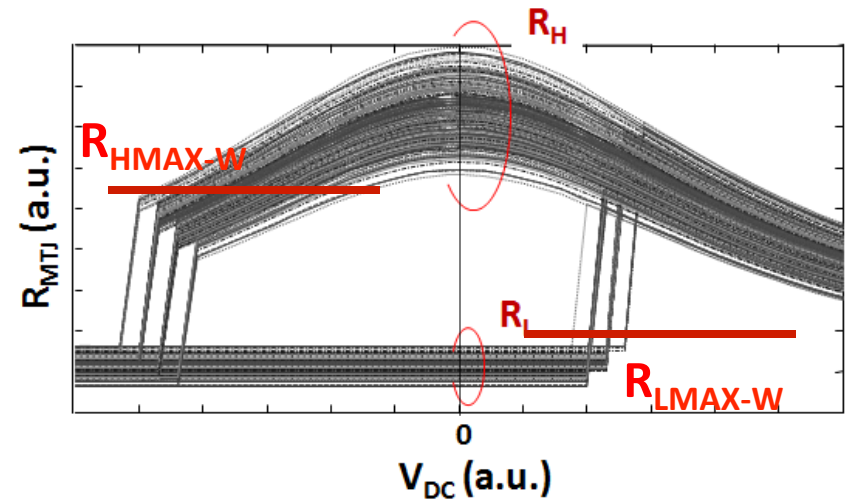
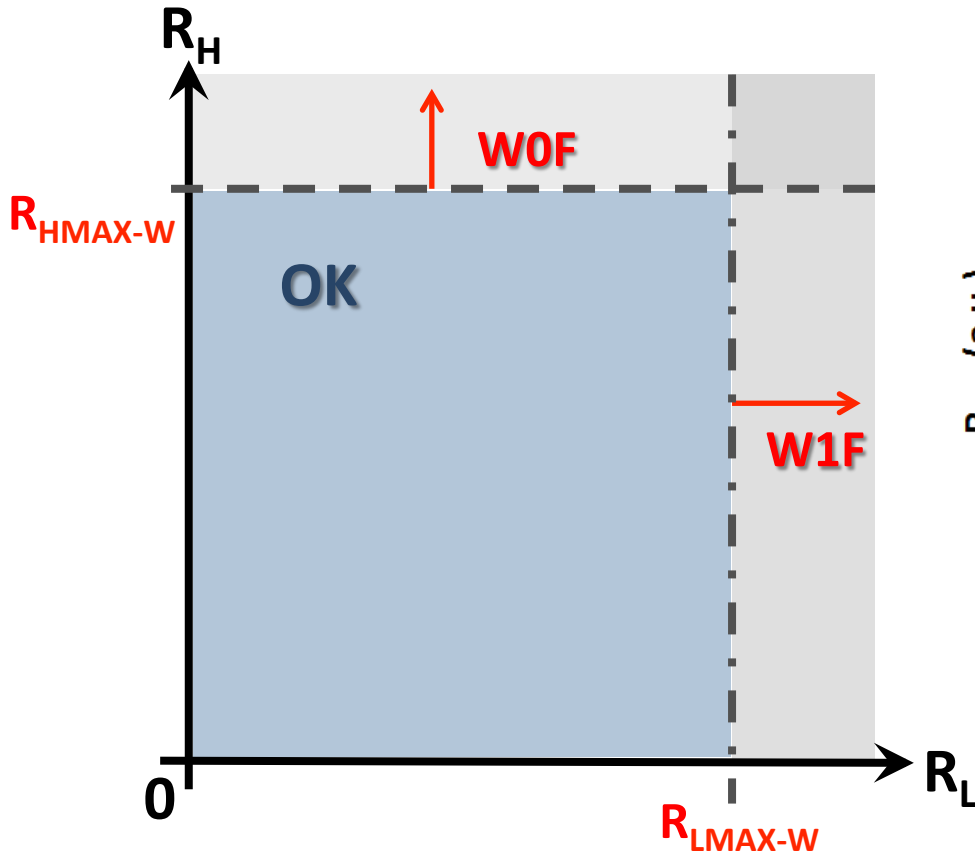
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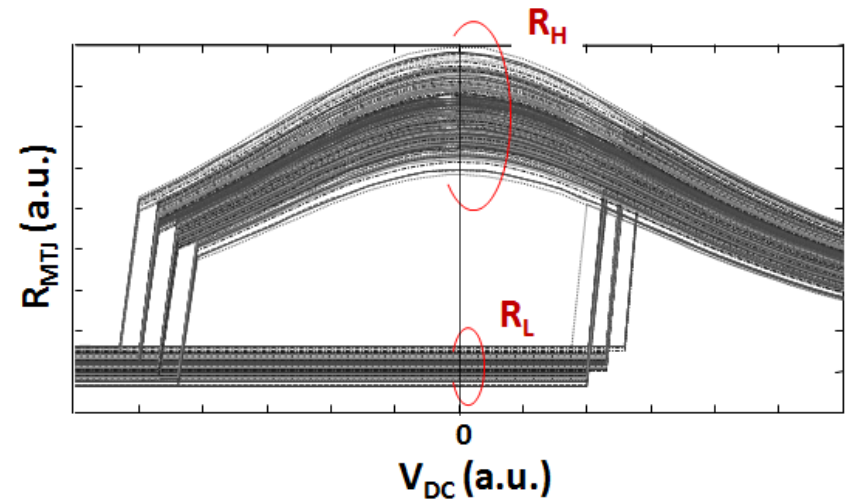
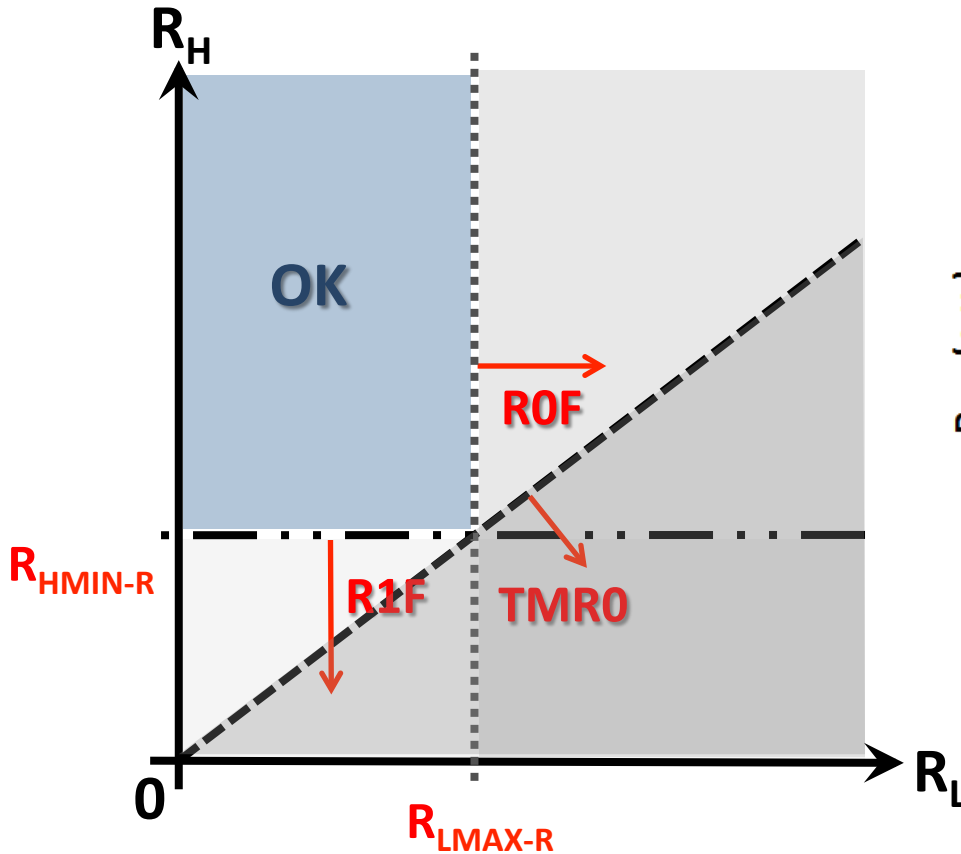
# STT-MRAM Failure Mechanisms



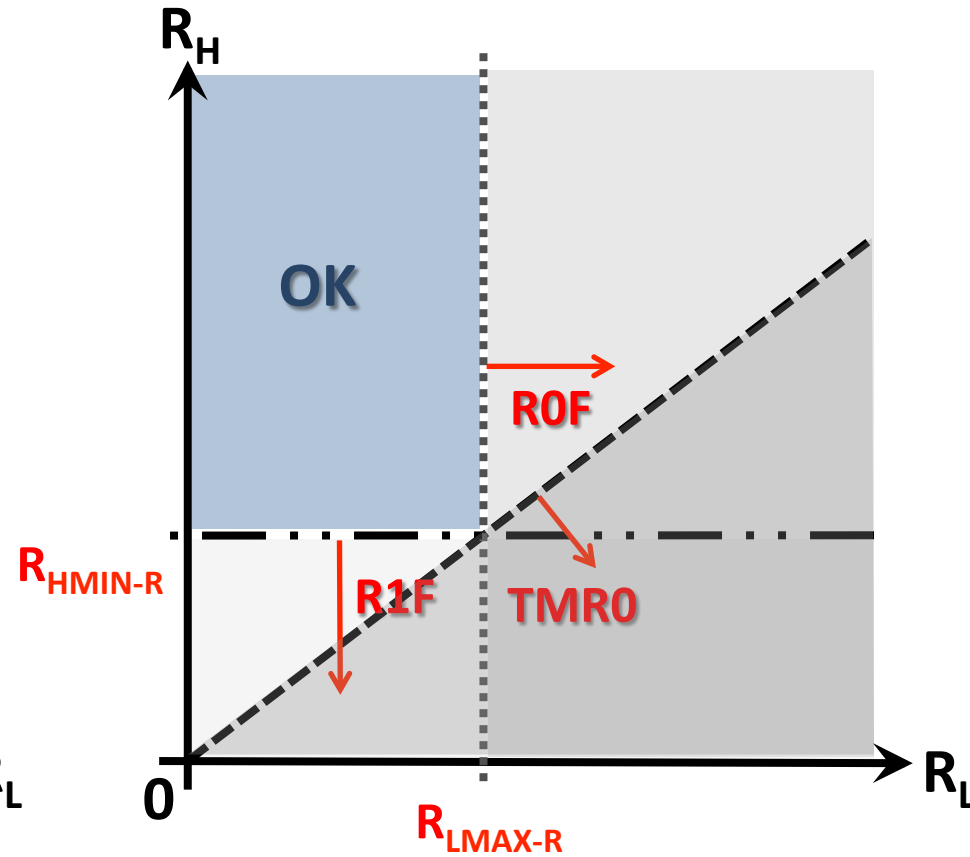
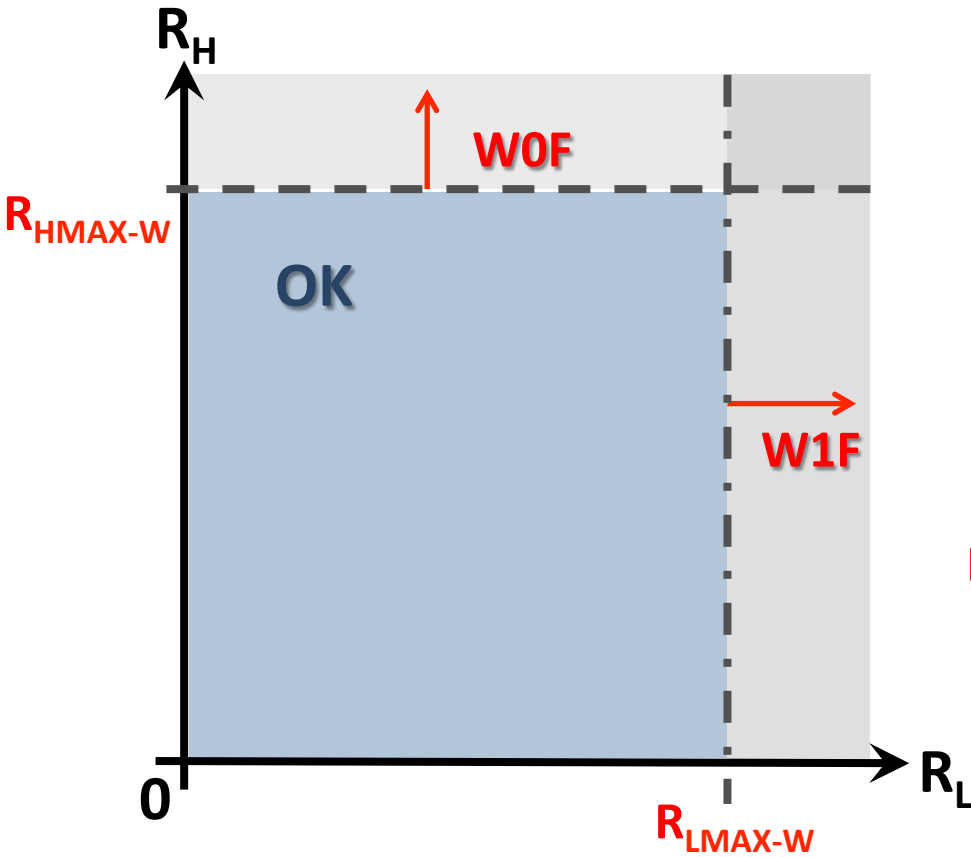
# STT-MRAM Failure Mechanisms



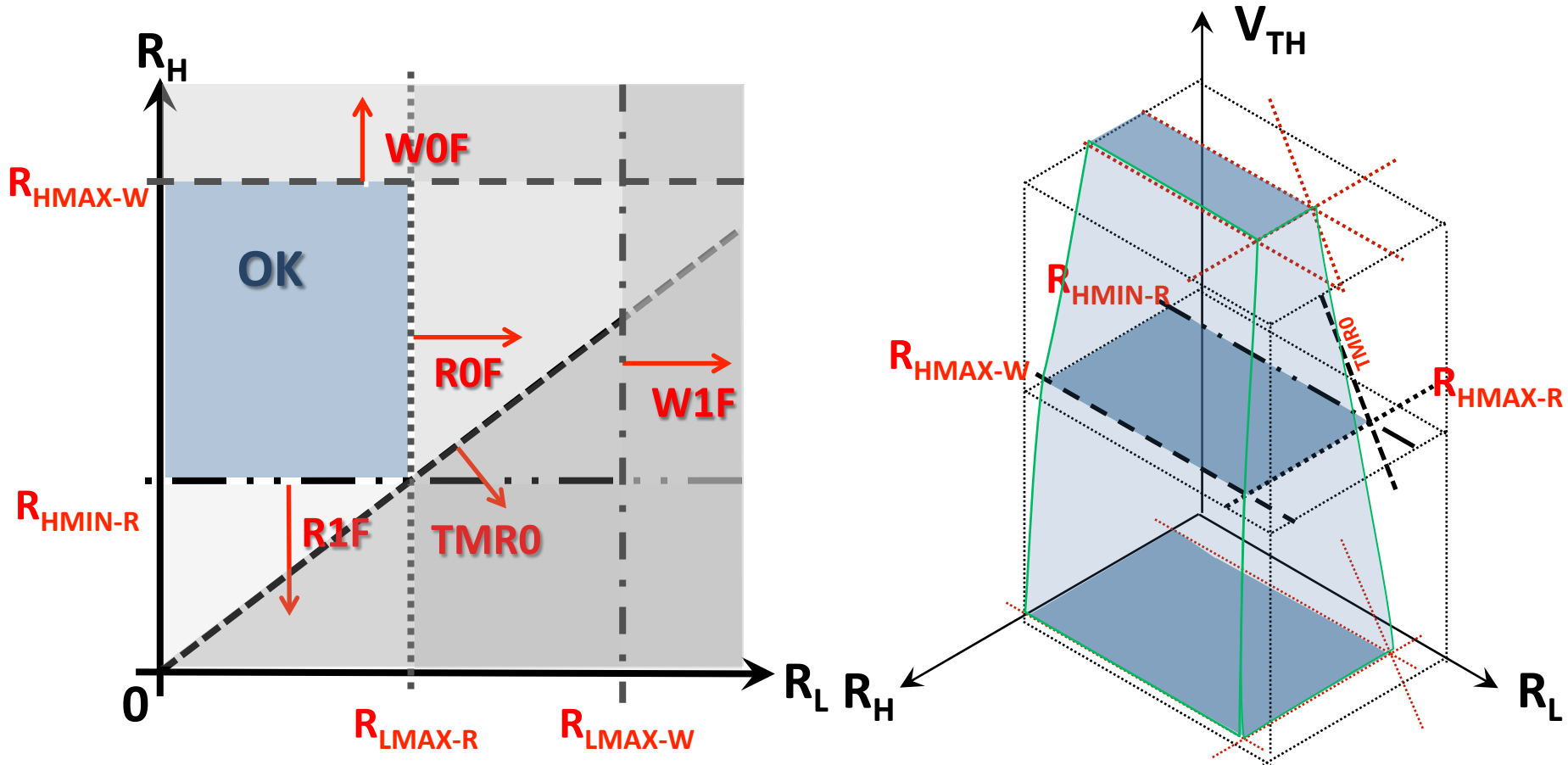
# STT-MRAM Failure Mechanisms



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# STT-MRAM Failure Mechanisms



$$P_{RF \& WF} = 1 - \int_0^{\min(R_{LMAX-R}, R_{LMAX-W})} \int_{R_{HMIN-R}}^{R_{HMAX-W}} \int_{V_{TH-min}}^{V_{TH-max}} f(R_L, R_H, V_{TH}) dR_L dR_H dV_{TH}$$

# *STT-MRAM Failure Mechanisms*

- Magnetic nanostructures suffer from thermally activated magnetization reversal.
- Néel-Brown: at finite temperature, there is a finite probability for the magnetization to flip and reverse its direction.
- Néel-Brown model:

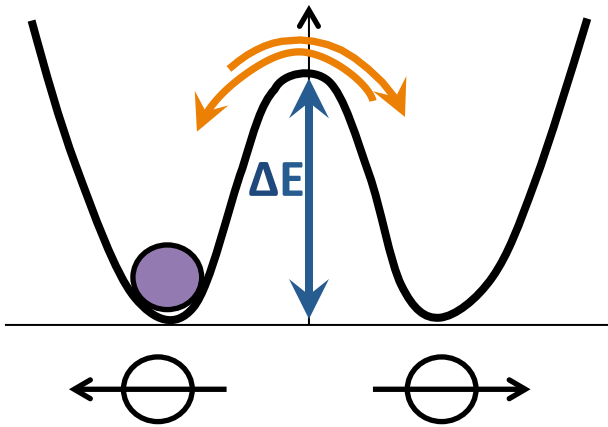
$$P(t) = \exp(-t/\tau)$$

$$\tau = \tau_0 \exp(\Delta E / k_B T)$$

# STT-MRAM Failure Mechanisms

- STT-MRAM Cell Failure Probability in Data Retention:

$$P(t) = 1 - \exp[(-Nt/\tau_0) \cdot \exp(-\Delta E/k_B T)]$$

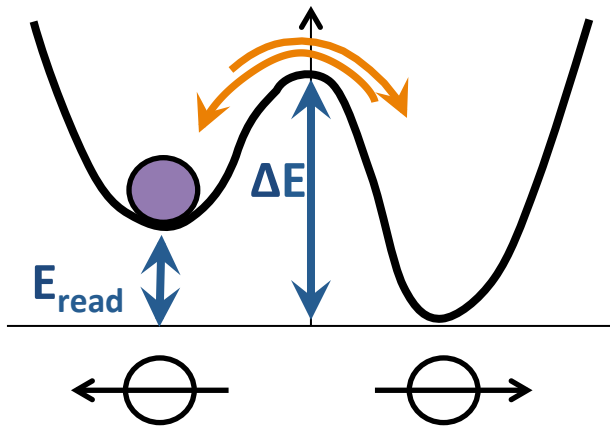




# STT-MRAM Failure Mechanisms

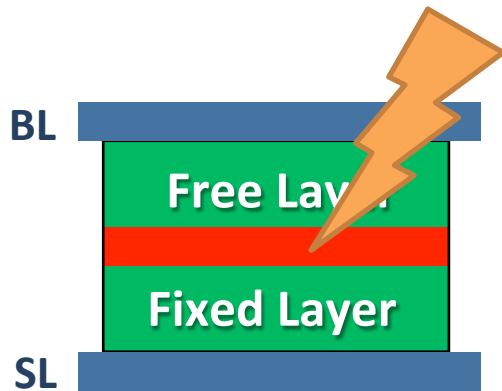
- STT-MRAM Cell Failure Probability in Read Operation

$$P(t) = 1 - \exp[-(Nt/\tau_0) \cdot \exp(-\Delta E(1 - (I_{read}/I_{OC}))/k_B T)]$$



# STT-MRAM Failure Mechanisms

- **Aging: STT-MRAM Cell Failure due to Tunneling Oxide Breakdown**



$R_H$  degradation due to Tunneling Oxide stress:

$$R_H(t) = \frac{R_H(0)}{1 + F(t)[R_H(0) / R_H(t_{BD}) - 1]}$$

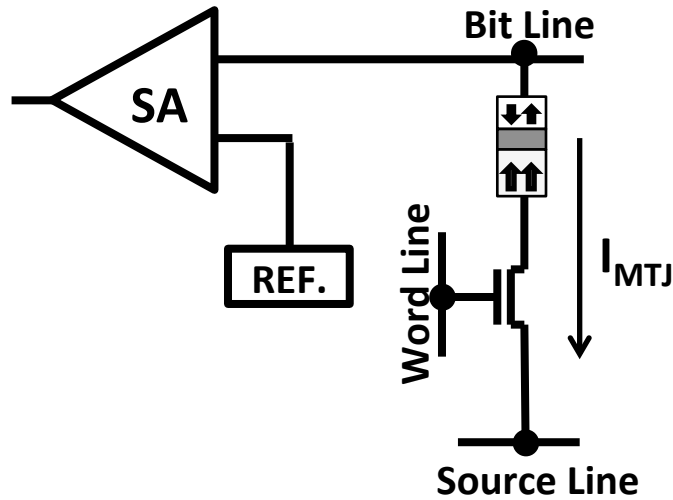
with  $F(t)$  following a Weibull distribution:

$$F(t) = 1 - \exp\left[-(t / \lambda)^k\right]$$

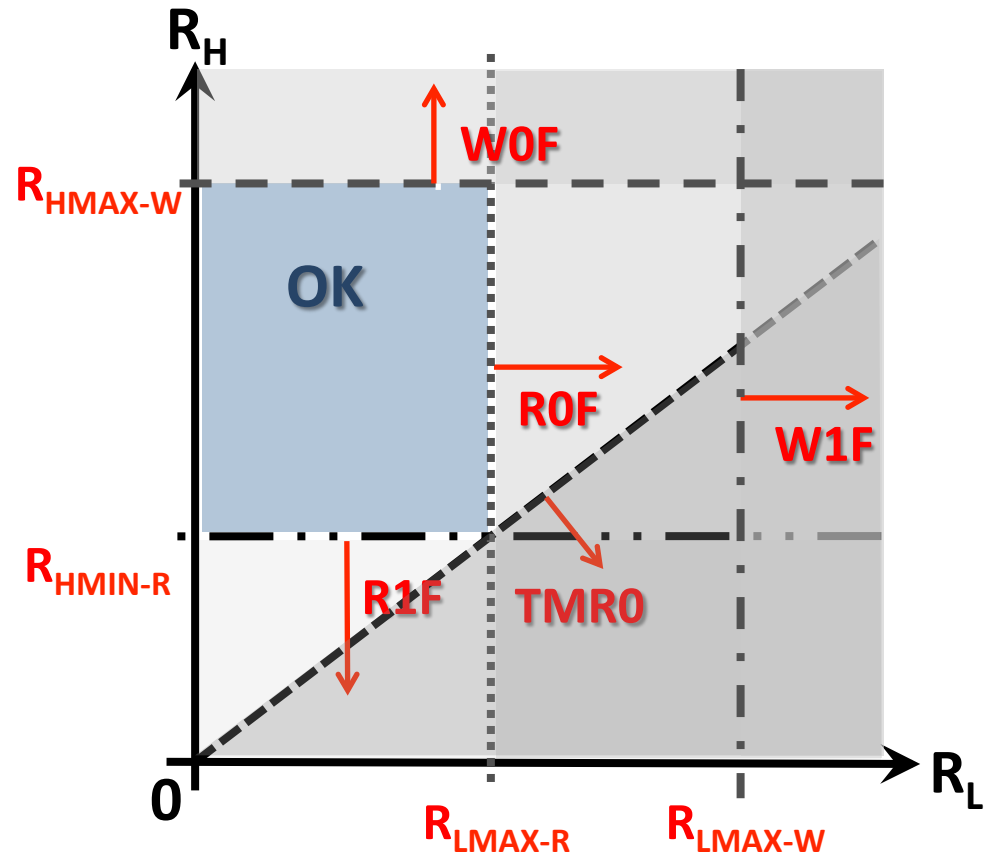
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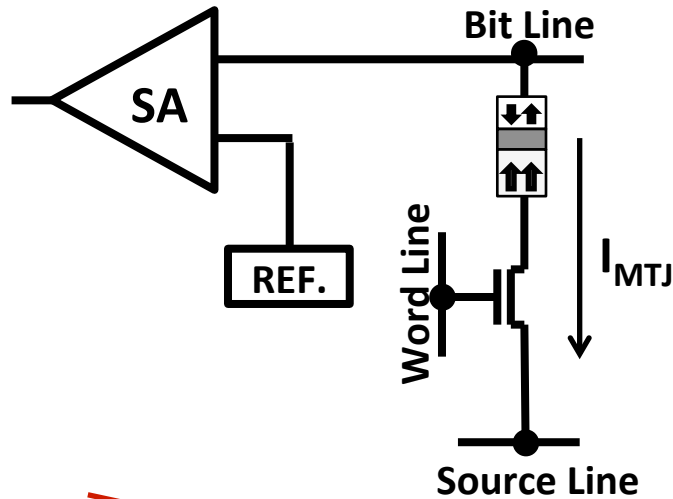
# Control voltage effect on STT MRAM cell operation



- Knobs
- $V_{DD}$
  - $V_{WL}$
  - $V_{BL-SL}$



# Control voltage effect on STT MRAM cell operation



Knobs

- $V_{DD}$
- $V_{WL}$
- $V_{BL-SL}$

~~$$P(t) = 1 - \exp[(-Nt/\tau_0) \cdot \exp(-\Delta E/k_B T)]$$~~

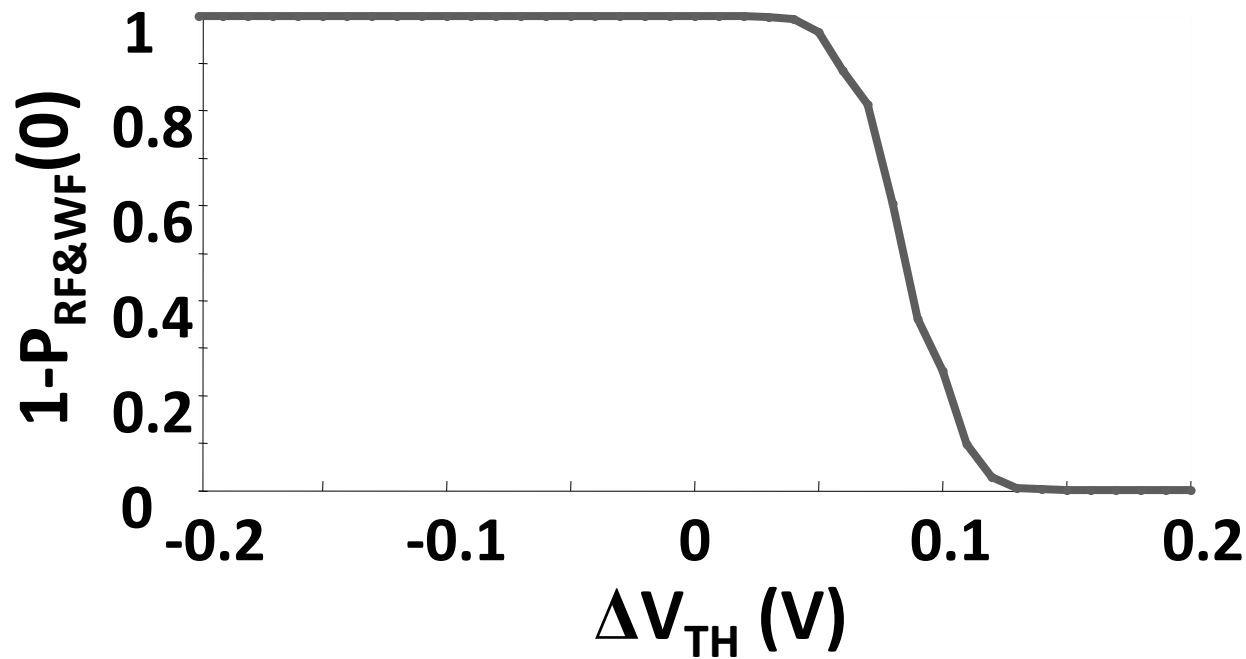
$$P(t) = 1 - \exp[(-Nt/\tau_0) \cdot \exp(-\Delta E(1 - (I_{read}/I_{OC}))/k_B T)]$$

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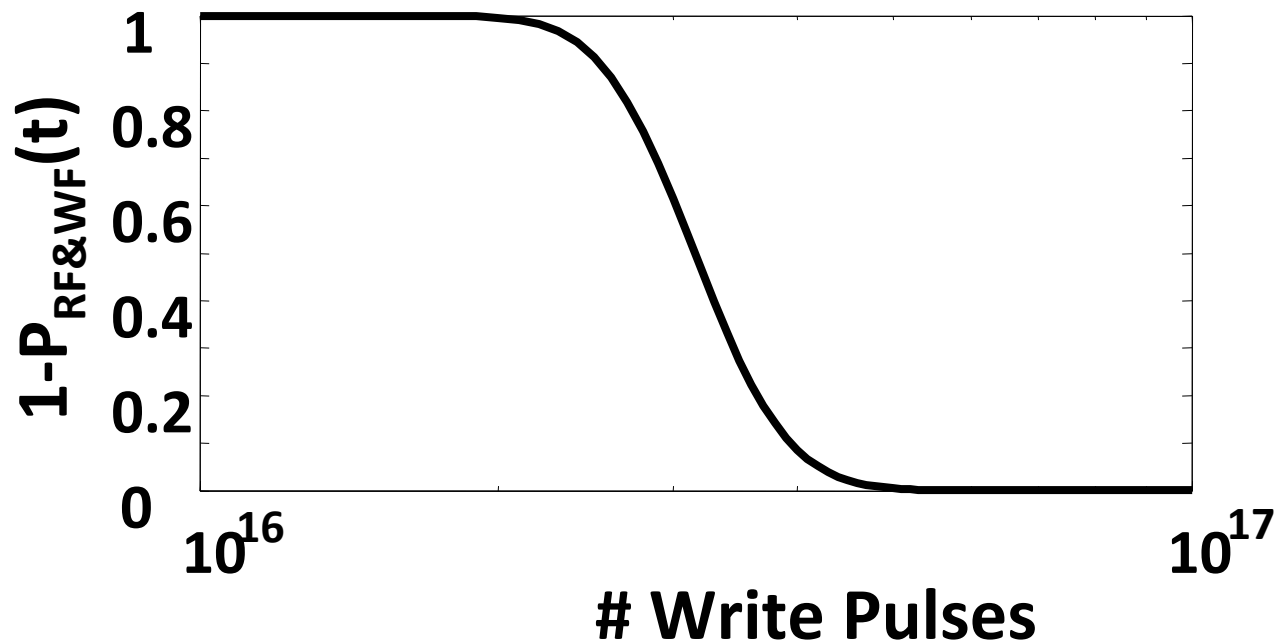
# STT-MRAM cell reliability

No knobs, Fresh Cell, 2D analysis with swipe  $V_{TH}$



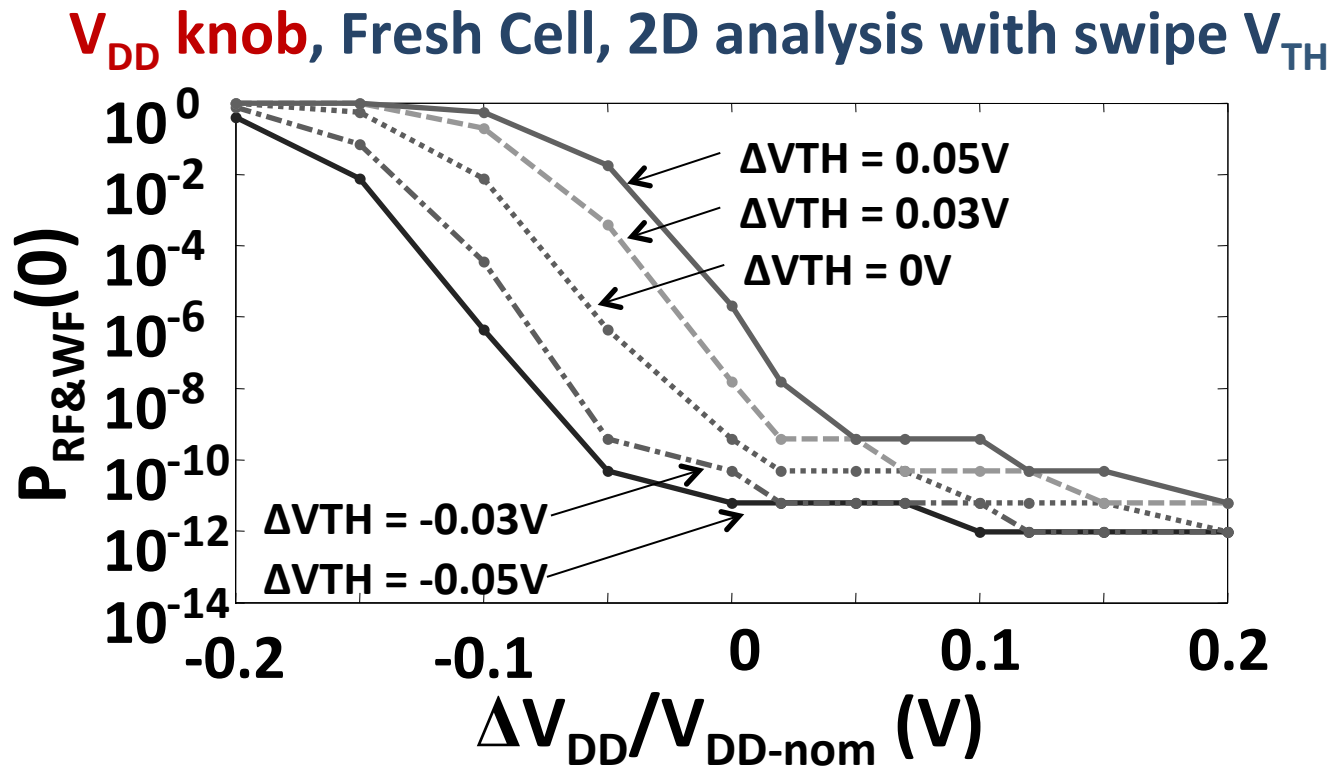
# STT-MRAM cell reliability

No knobs, Aged Cell, 3D analysis



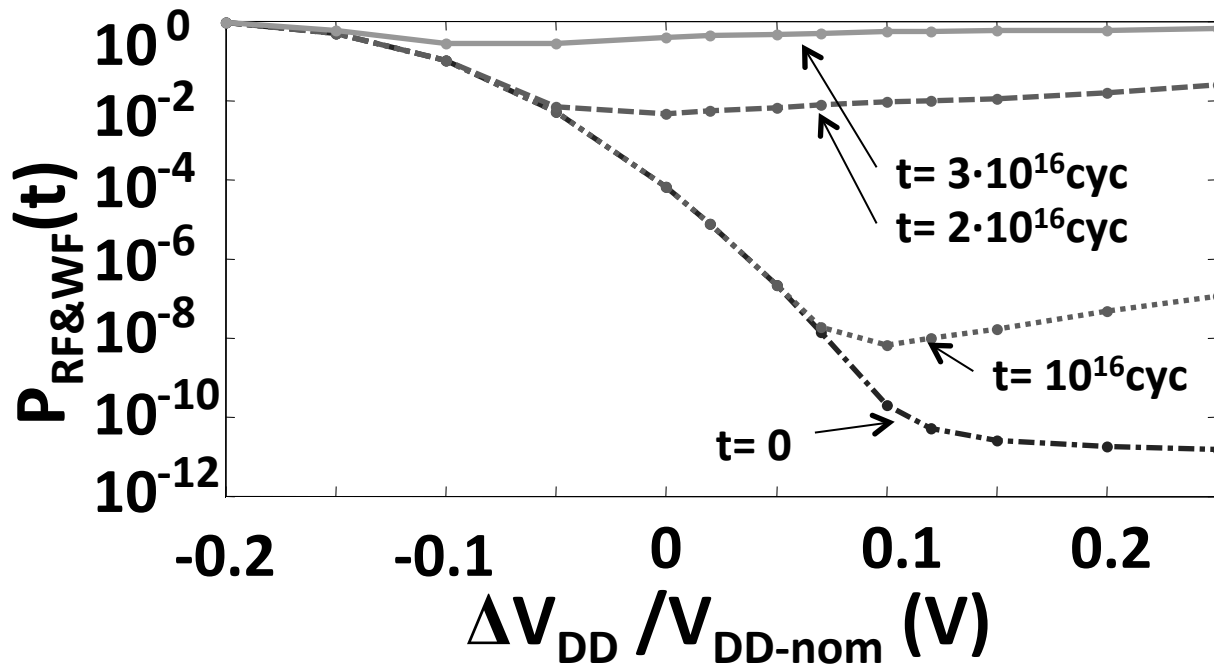


# STT-MRAM cell reliability



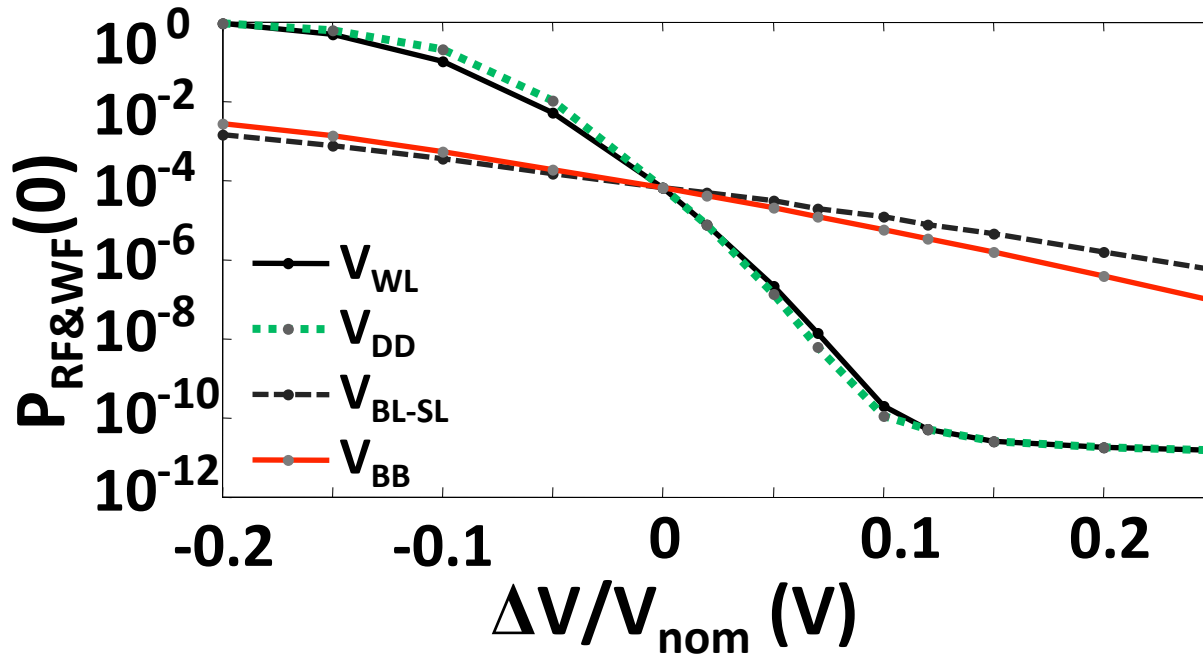
# STT-MRAM cell reliability

## $V_{DD}$ knob, Aged Cell, 3D analysis



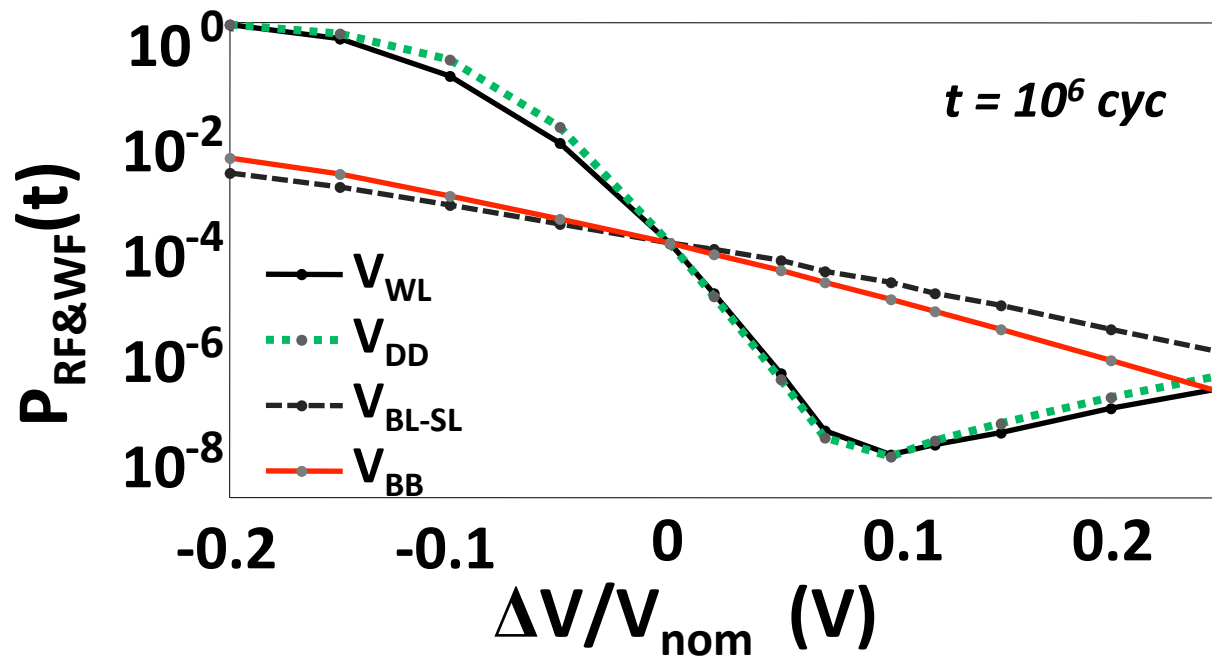
# STT-MRAM cell reliability

All knobs, Fresh Cell, 3D analysis



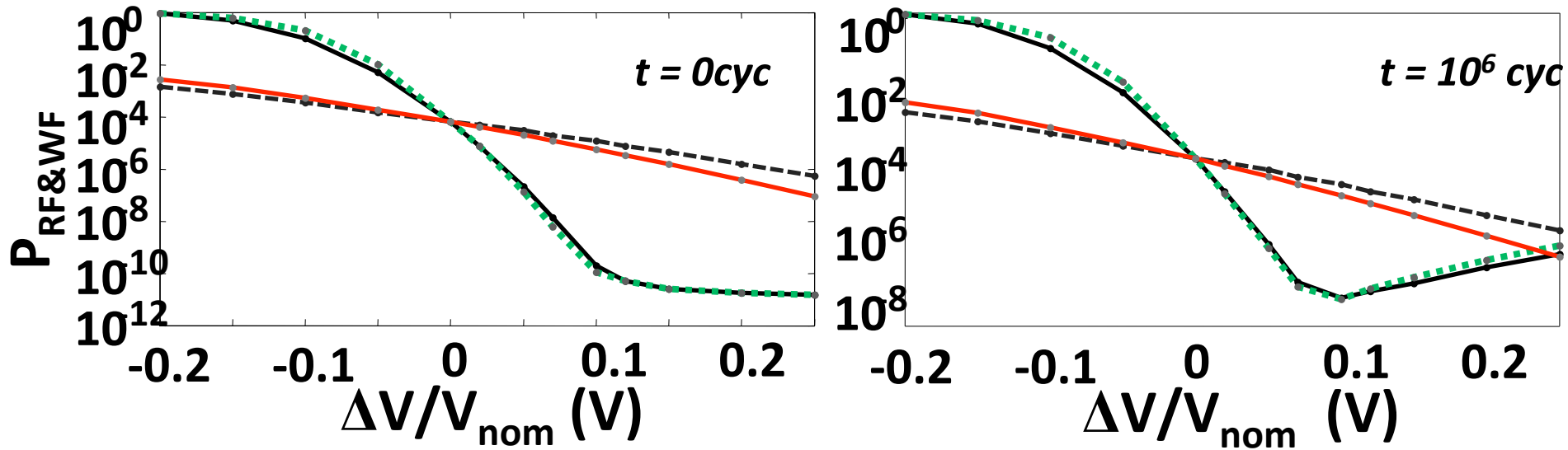
# STT-MRAM cell reliability

All knobs, Fresh Cell, 3D analysis



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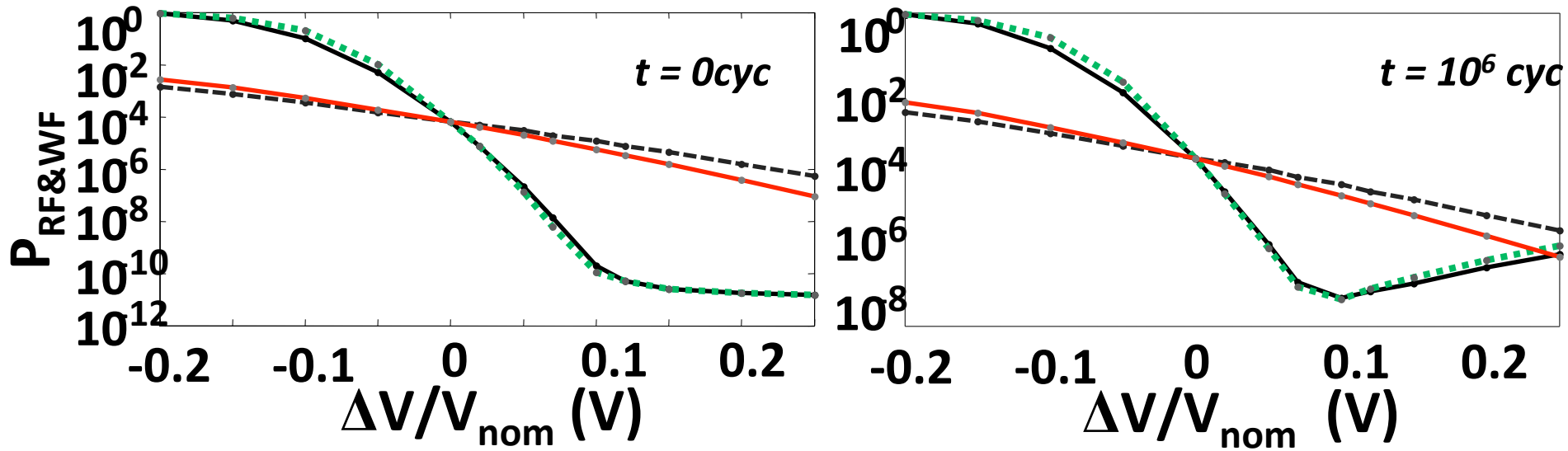
All knobs, 3D analysis



- $V_{WL}$
- $V_{DD}$
- - -  $V_{BL-SL}$
- $V_{BB}$

# STT-MRAM cell reliability

All knobs, 3D analysis

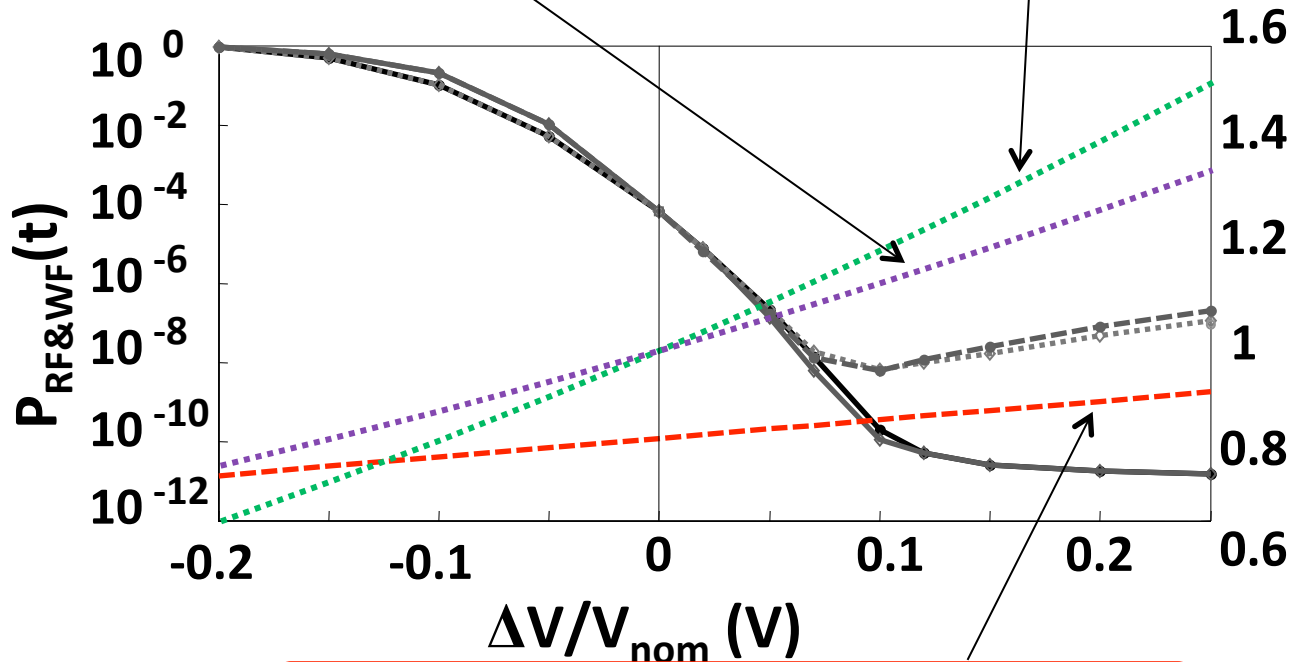


- $V_{WL}$
- $V_{DD}$
- - -●- -  $V_{BL-SL}$
- $V_{BB}$

# Reliability Power Tradeoff

Power Consumption when varying  $V_{WL}$

Power Consumption when varying  $V_{DD}$



Failure Probability due to Read Disturb (RD)

Relative Power Consumption

- $V_{WL}@t=0$
- $V_{DD}@t=0$
- - -  $V_{WL}@t=10^{16}$  cyc
- · -  $V_{DD}@t=10^{16}$  cyc

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# Conclusions

- **STT-MRAM reliability evaluation methodology**
- **The joint effect of**
  - **fabrication- and aging-induced process variability**
- **Reliability evaluation under voltage tuning**
- **Power aware reliability estimation to identify optimum voltage value for STT-MRAM operation**

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